



# Process Change Notification

PCN Number: PCN- 000013

PCN Notification Date: 08/16/2023

## Informational PCN

Addition of 2<sup>nd</sup> source (Advantek) Carrier & Cover Material for both SSOP 20L / 28L package types

Dear Customer,

This Informational PCN notification is to advise you of the following change(s).

- Addition of a 2<sup>nd</sup> Source Cover Tape Material:
  - (Advantek) HUF0133
- Addition of a 2<sup>nd</sup> Source Carrier Tape Material:
  - (Advantek) SSOP20-C for SSOP 20L
  - (Advantek) SSOP28-C for SSOP 28L

Note: Vendor (Advantek) is already a qualified supplier, and the specified cover and carrier tape material are already utilized in mass production on other product.

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator  
Cirrus Logic Corporate Quality  
Phone: +1(512) 851-4000



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## Products Affected:

The devices listed on subsequent pages are the complete list of affected devices. According to our records, one or more of these devices have been purchased by your organization within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

<b>Title:</b>	Addition of 2 <sup>nd</sup> source (Advantek) Carrier & Cover Material for both SSOP 20L / 28L package types				
<b>Customer Contact:</b>	Local Field Sales Representative	<b>Phone :</b>	(512) 851-4000	<b>Dept:</b>	Corporate Quality
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Immediate	<b>Estimated Sample Availability Date:</b>			Not Applicable
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Process	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Process	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Design
<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Part Number
X	Packing/Shipping/Labeling	<input type="checkbox"/>	Other	<input type="checkbox"/>	
<b>Comments:</b>	Addition of ADVANTEK HUF0133 as a 2 <sup>nd</sup> cover tape source and ADVANTEK SSOP20-C/SSOP28-E as 2 <sup>nd</sup> carrier tape sources				

## PCN Details

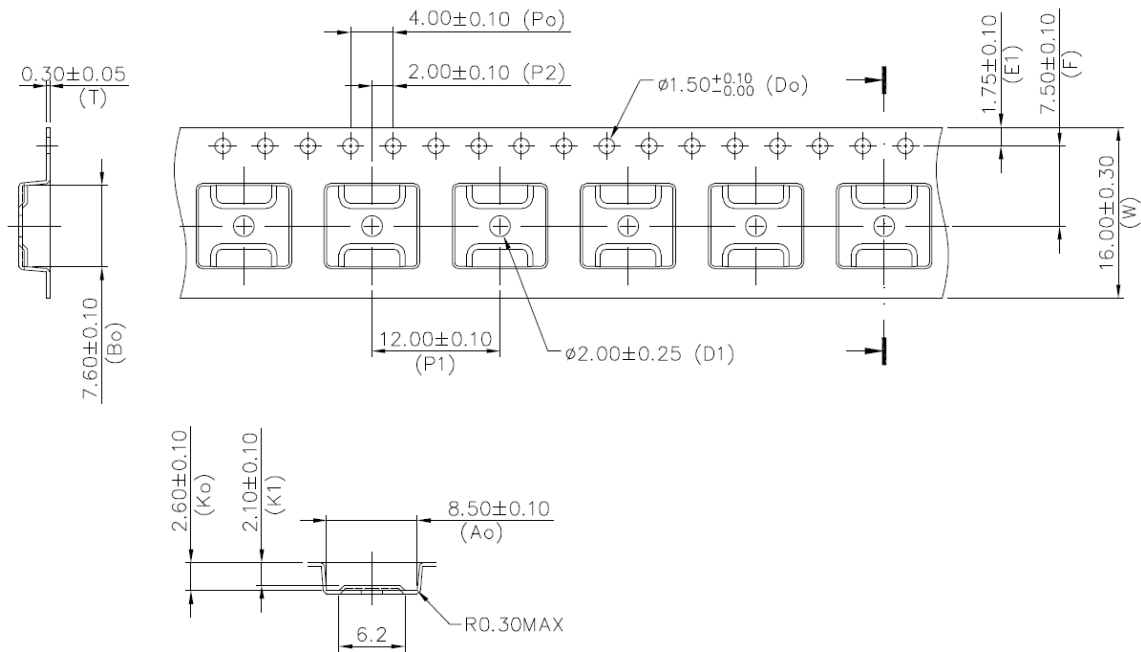
### Description of Change(s):

Addition of second source for carrier and cover tapes for both SSOP 20L and 28L package types.

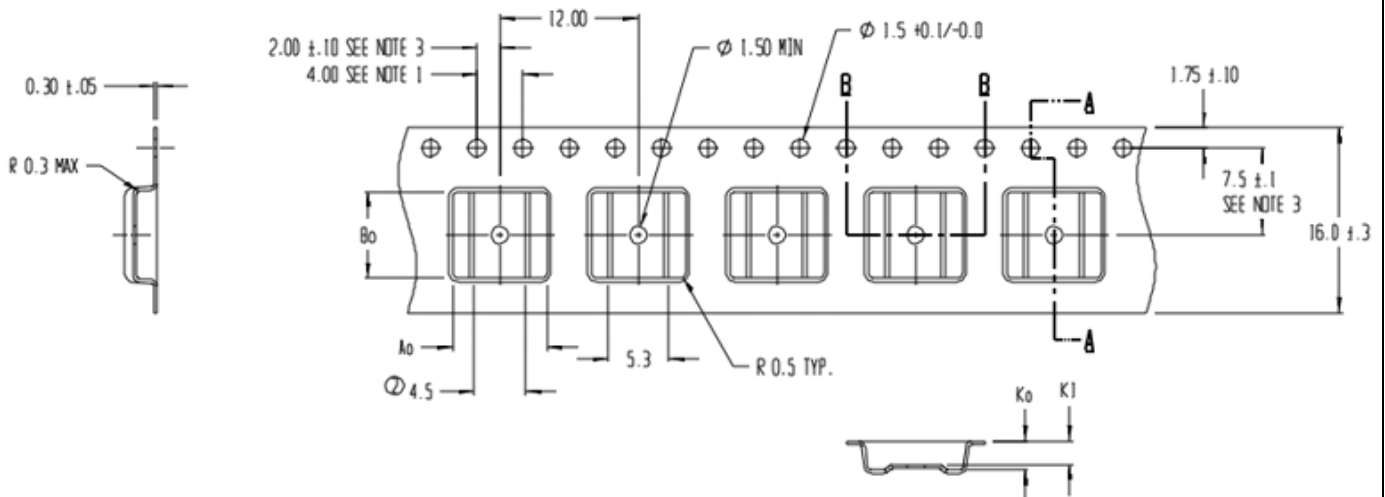
- Carrier tape change for SSOP 20L

ITEM	CURRENT	NEW
Supplier	HWA SHU	ADVANTEK
Part number	ECI070803	SSOP20-C
A0 (mm)	8.5+/-0.1	8.2+/-0.1
B0 (mm)	7.6+/-0.1	7.5+/-0.1
K0 (mm)	2.1+/-0.1	2.5+/-0.1
P1 (mm)	12.0+/-0.1	12.0+/-0.1
W (mm)	16.0+/-0.3	16.0+/-0.3
T (mm)	0.3+/-0.05	0.3+/-0.05
F (mm)	7.5+/-0.1	7.5+/-0.1
P2 (mm)	2.0+/-0.1	2.0+/-0.1
RoHS compliant	Yes	Yes
EIA-481 compliant	Yes	Yes
ESD compliance	1E4~1E11 Ohms/sq.	1E5~1E10 Ohms/sq.

○ **Current Carrier tape drawing**



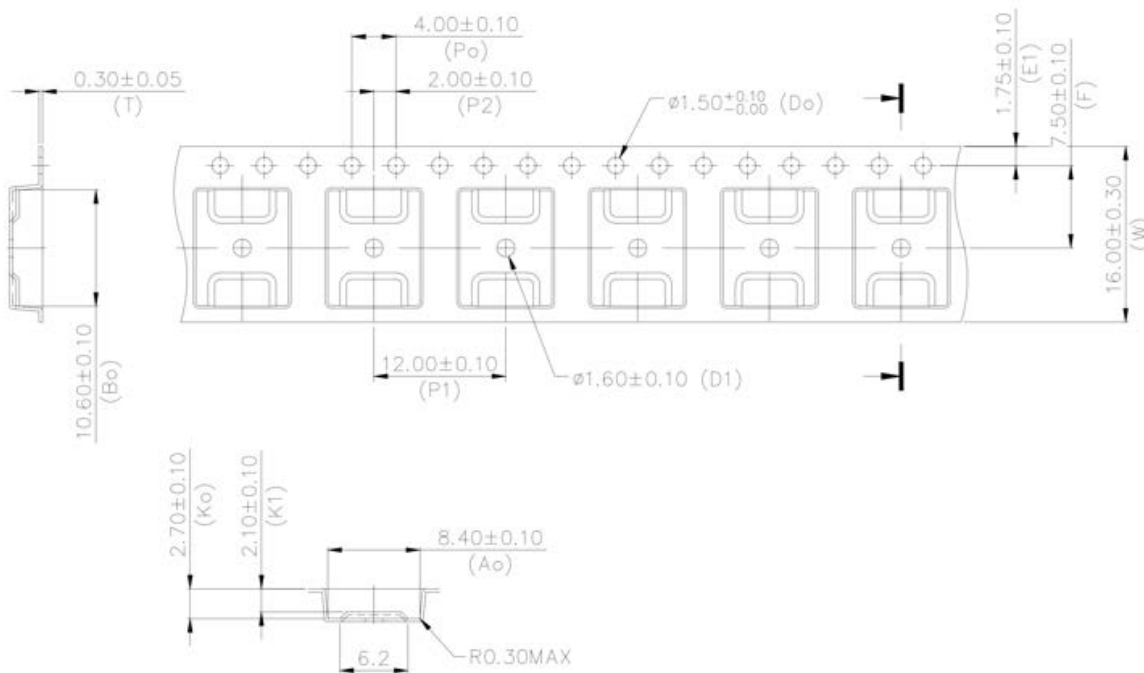
○ **New Carrier tape drawing**



- Carrier tape change for SSOP 28L

ITEM	CURRENT	NEW
Supplier	HWA SHU	ADVANTEK
Part number	ECI081002	SSOP28-E
A0 (mm)	8.4+/-0.1	8.4+/-0.1
B0 (mm)	10.6+/-0.1	10.65+/-0.1
K0 (mm)	2.7+/-0.1	2.4+/-0.1
P1 (mm)	12.0+/-0.1	12.0+/-0.1
W (mm)	16.0+/-0.3	16.0+/-0.3
T (mm)	0.3+/-0.05	0.3+/-0.05
F (mm)	7.5+/-0.1	7.5+/-0.1
P2 (mm)	2.0+/-0.1	2.0+/-0.1
RoHS compliant	Yes	Yes
EIA-481 compliant	Yes	Yes
ESD compliance	1E4~1E11 Ohms/sq.	1E5~1E10 Ohms/sq.

- Current Carrier tape drawing





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Item	Current	New
Part number	ED16-1330-216	HUF0133
Vender	HWA SHU	ADVANTEK
Dimension (Thick)	0.06+ - 0.01mm	0.05+ - 0.005mm
Dimension (Tape Width)	13.3+/-0.1mm	13.3+/-0.1mm
Seal Type	Heat Activated	Heat Activated
Break strength	≥7000PSI	10500PSI
RoHS compliant	Yes	Yes
EIA-481 compliant	Yes	Yes
ESD compliance	1E5~1E12 Ohms/sq.	1E5~1E10 Ohms/sq.

Existing supply of cover tape material no longer available and phasing out.

No anticipated adverse impact to the Quality and/or Reliability of said product.

<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release.
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### Product Affected:

#### Cirrus Logic Part Number(s):

WM8716SEDS/RV	WM8569SEDS/RV
WM8196SCDS/RV	WM8741GEDS/RV
WM8199SCDS/RV	WM8742GEDS/RV
WM8213SCDS/RV	WM8766GEDS/RV
WM8214SCDS/RV	WM8782ASEDS/RV
WM8740SEDS/RV	WM8804GEDS/RV
WM8731SEDS/RV	WM8805GEDS/RV

### Changes To Product Identification Resulting From This PCN:

All Product Identification remains the same

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## Evaluation Result

Evaluation: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Evaluation Item	Comparison Basis	Sample Size (PASS/FAIL)
Peeling Strength	Peel strength comparable to previous carrier tape	10 samples <b>Passed</b>
Dimension Measurement-cover	Comparable with existing materials	1 roll <b>Passed</b>
Dimension Measurement-carrier	Comparable with existing materials	1 roll <b>Passed</b>
Surface resistivity	Cirrus spec $10^5 \sim 10^{10}$ ohms/sq Within Cirrus spec (3-SUPP-00069)	1 roll <b>Passed</b>
Lead Scan and TnR	100% yield	200 samples <b>Passed</b>
Drop Test	Zero failure Within Cirrus spec (3-SUPP-00506)	2000 samples <b>Passed</b>
<b>Notes:</b> <ul style="list-style-type: none"><li>Evaluation tests “pass” on zero fails for each test.</li></ul>		